

Schottky Surface Mount Flat Bridge Rectifier

Features

- Surge overload rating:30 amperes peak
- Ideal for printed circuit board
- Plastic material has Underwriters Laboratory Flammability Classification 94V-0
- Low leakage
- Reliable low cost construction utilizing molded



RoHS
COMPLIANT



Mechanical Date

- **Case:** Molded plastic,MBF
- **Terminals: Leads** solderable per MIL-STD-202 method 208 guaranteed
- **EPOXY:**UL 94V-0 rate flame retardant
- **Mounting position:** Any

Major Ratings and Characteristics

I_F	2A
V_{RRM}	20 V to 100 V
I_{FSM}	50A
I_R	500 μ A
V_F	0.5V,0.55V,0.7V,0.85V
T_j max.	150 °C

Maximum Ratings & Thermal Characteristics (TA = 25 °C unless otherwise noted)

Items	Symbol	KMB 22F	KMB 24F	KMB 26F	KMB 28F	KMB 210F	UNIT	
Peak Repetitive Reverse Voltage	V_{RRM}							
Working Peak Reverse Voltage	V_{RWM}	20	40	60	80	100	V	
DC Blocking Voltage	V_R							
RMS Reverse Voltage	$V_{R(RMS)}$	14	28	42	56	70	V	
Maximum average forward rectified current 0.2×0.2"(5.0×5.0mm) copper pad area	$I_{F(AV)}$	2						A
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load	I_{FSM}	50						A
Maximum instantaneous forward voltage at 2.0A	V_F	0.5	0.55	0.7	0.85		V	
Maximum DC reverse current TA=25°C at Rated DC blocking voltage TA=100°C	I_R	0.5 20						mA
Typical Junction Capacitance at 4.0V,1.0MHz	C_J	250			125		°C/ W	
Typical Thermal resistance (Note1)	$R_{\theta JA}$ $R_{\theta JL}$	85 20						°C/ W
Operating junction temperature range	T_J	-55 to +125						°C
storage temperature range	T_{STG}	-55 to +150						°C

Note 1: Thermal resistance from junction to ambient and junction to lead P.C.B.mounted on 0.2×0.2"(5.0×5.0 mm) copper pad areas

Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

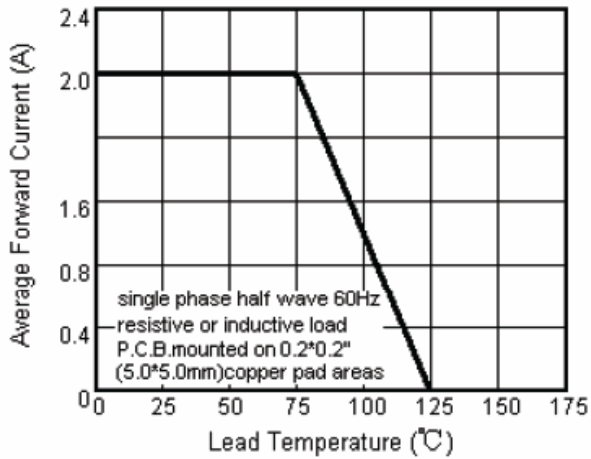


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

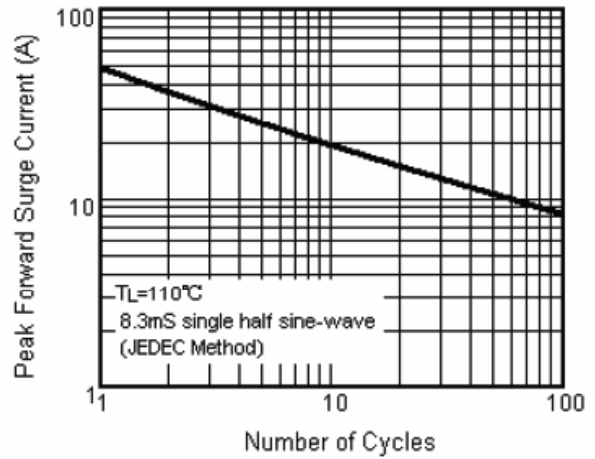


Fig.3 Typical Instantaneous Forward Characteristics

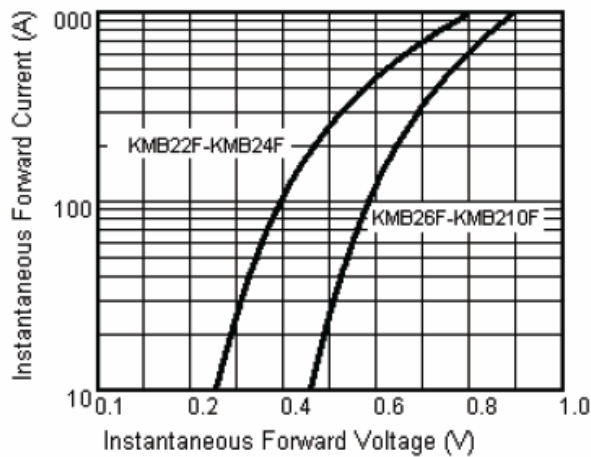
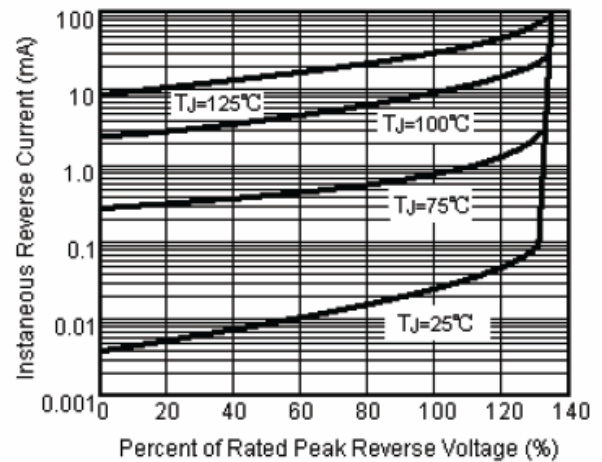
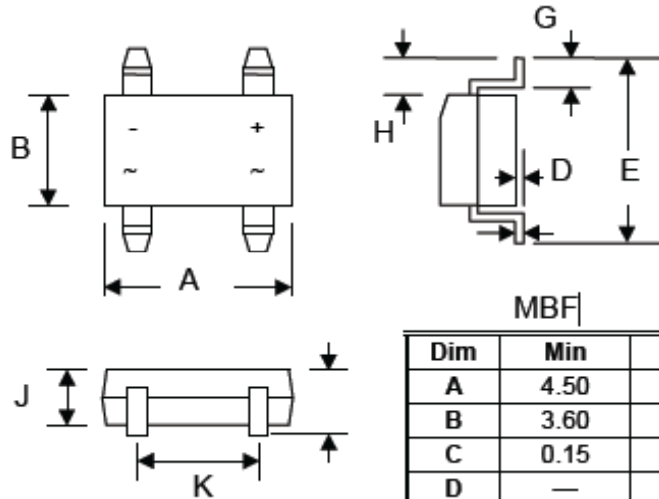


Fig.4A Typical Reverse Characteristics



Package Outline

MBF



MBF

Dim	Min	Max
A	4.50	4.95
B	3.60	4.10
C	0.15	0.35
D	—	0.20
E	6.40	7.00
G	0.50	1.10
H	1.30	1.70
J	1.20	1.60
K	2.30	2.70
L	—	1.80
All Dimensions in mm		

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